

HSPF

NOTES:

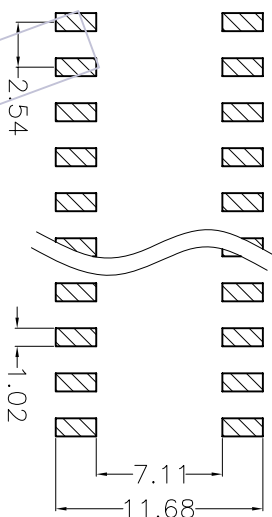
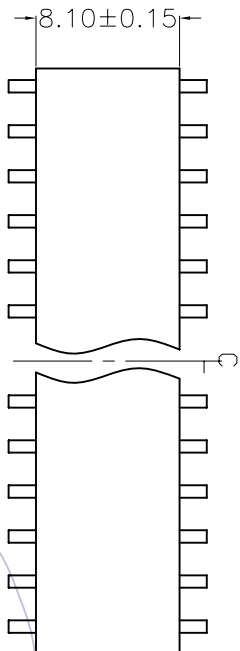
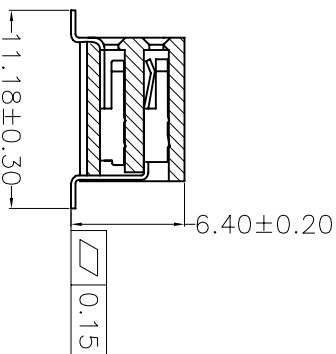
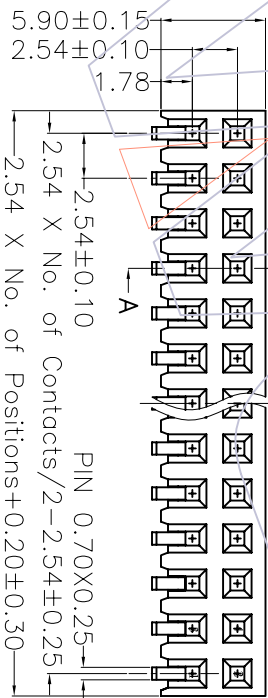
Current Rating: 3.0AMP
 Withstand Voltage: 500V AC/DC
 Contact Resistance: 20mΩ Max
 Insulation Resistance: 1000MΩMin
 Operation Temperature: -40°C to +105°C
 Contact Material: Phosphor Bronze
 Contact plating: Au or Sn over Ni
 Insulator Material: PA6T+30%G, F UL94V-0

Ordering Information

2159 - 2 XX M XX C UN X 1

No. of Pins per Row: 502-40PIN
 Contact Plating:
 C0=Gold Flash
 G1=3μ"Gold
 G2=5μ"Gold
 G3=10μ"Gold
 G4=5μ"Gold
 G5=30μ"Gold
 S0=Gold Flash/Tin
 S1=3μ"Gold/Tin
 S2=5μ"Gold/Tin
 S3=10μ"Gold/Tin
 S4=5μ"Gold/Tin
 S5=30μ"Gold/Tin
 SN=Tin

Packing:
 T=Tube
 R=Reel



Recommended P.C.B Layout(TOP Side)
 (PCB BOARD TOLERANCE±0.05)

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|-----|----------|--------------------------|--------|---------|---|-----------------|-------|----------|--|-------|--|------------------------|-----------------------|
| REV | DATE | MODIFICATION DESCRIPTION | CHANGE | APPROVE | OPERATION | DRAW | WEIXD | 08.03.11 | SCALE | 2.5:1 | WCON 维峰五金电子有限公司 WAFER HARDWARE ELECTRONICS CO.,LTD | PART NO. | 2159-2XXMXXCUNX1 |
| A0 | 08/03/11 | NEW | | | XXX ±0.40 XXX ±0.25 XXX ±0.15 Angle ± 3' | DESIGN CHECK | | | UNIT mm SIZE A4 SHEET 1/1 | PROJ. | | TITLE: Customer NO. | FH2.54 DUAL SMT H=5.9 |